

ABSTRACT

A technique is provided for communicatively coupling internal circuitry (e.g., a resonant tank) of an integrated circuit (“IC”) with pins of the IC’s package in a manner that minimizes the inductance of such coupling. In certain embodiments, more than two bondwires are coupled to an electrically common interface, wherein the bondwires are used for carrying a signal of the internal circuitry of the IC. More particularly, in certain implementations the bondwires are used as inductors for the internal circuitry (e.g., a resonant tank) of the IC. In certain embodiments, a plurality of bondwires are coupled to a plurality of IC package pins, which are electrically coupled together. By carrying signals of opposite polarity on each of the bondwires, the inductance of such bondwires is minimized.